

REMARKS

Reconsideration and allowance of this application are respectfully requested in light of the above amendments and the following remarks.

Claim 5 has been amended for formalities. The amendment is non-narrowing; therefore no estoppel should be deemed to attach thereto.

Claims 3, 4, 6-8, and 10-12 stand withdrawn as being directed toward non-elected subject matter.

Claims 1, 2, 5, and 9 stand rejected, under 35 USC § 102(b), as being anticipated by Koichi et al. (JP 05-244690). The Applicants respectfully traverse these rejections based on the points set forth below.

Claim 1 defines an ultrasonic probe having a heat conduction material within a backing load member or a part thereof. The claimed subject matter provides an advantage of reducing the heat radiated from the ultrasonic probe to a patient so that more power may be applied to the probe, thereby increasing the diagnostic depth of the ultrasonic radiation (see the illustrative discussion at specification page 4, lines 5-19, and page 5, lines 12-17).

The Office Action proposes that Koichi discloses a heat conduction material 14 disposed within a packing material 5, which the Office Action construes as the claimed backing load member (see Office Action Section 4). However, as illustrated by Koichi in Fig. 1, a heat radiating base 6 is sandwiched between Koichi's packing material 5 and heat conduction member 14. Thus, Koichi's heat conduction member 14 is not disposed within a backing material (e.g., packing material 5), as is the claimed heat conduction member. Moreover, Koichi does not teach

anything regarding the conductivity of heat between packing material 5 and heat conduction member 14.

Accordingly, the Applicants respectfully submit that Koichi does not anticipate the subject matter defined by claim 1. Independent claim 2 similarly recites the above-mentioned subject matter distinguishing claim 1 from Koichi. Therefore, allowance of claims 1 and 2 and all claims dependent therefrom is warranted.

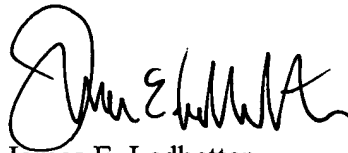
With regard to claim 5, the Office Action proposes that Koichi discloses the claimed heat radiating block (i.e., Koichi's pedestal 6) that is connected to a heat conduction material (see Office Action section 6). However, as illustrated in Koichi's Fig. 1, Koichi's pedestal 6 is not connected to heat conduction material 14, since a metallic thin film 7 and a fixing plate 15 are disposed between Koichi's pedestal 6 and heat conduction material 14. Moreover, claim 5 recites that the thermal conductivity of the heat radiating block is greater than the thermal conductivity of the backing load member, whereas Koichi does not teach anything about thermal conductivity. Accordingly, allowance of claim 5 is deemed to be warranted for these independent reasons.

With regard to claim 9, the Office Action proposes that Koichi discloses, in paragraph 7, the claimed heat conduction material having a PGS graphite sheet with a high degree of orientation and a polymeric film that is graphitized, graphite, carbon nano-tube, aluminum nitride, boron nitride, silicon carbide, beryllium oxide, copper, or aluminum (see Office Action section 7). The Applicants respectfully submit that Koichi does not disclose such subject matter in paragraph 7. Accordingly, allowance of claim 9 is considered to be warranted for this independent reason.

In view of the above, it is submitted that this application is in condition for allowance,
and a notice to that effect is respectfully solicited.

If any issues remain which may best be resolved through a telephone communication, the
Examiner is requested to telephone the undersigned at the local Washington, D.C. telephone
number listed below.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "James E. Ledbetter". The signature is stylized with a large initial "J" and a cursive "E".

James E. Ledbetter
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JEL/DWW/att

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